Trenz Electronic GmbH - TE0820-02-03CG-1EA Datasheet

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Understanding Embedded - Microcontroller, Microprocessor, FPGA Modules

Embedded - Microcontroller, Microprocessor, and FPGA Modules are fundamental components in modern electronic systems, offering a wide range of functionalities and capabilities. Microcontrollers are compact integrated circuits designed to execute specific control tasks within an embedded system. They typically include a processor, memory, and input/output peripherals on a single chip. Microprocessors, on the other hand, are more powerful processing units used in complex computing tasks, often requiring external memory and peripherals. FPGAs (Field Programmable Gate Arrays) are highly flexible devices that can be configured by the user to perform specific logic functions, making them invaluable in applications requiring customization and adaptability.

Applications of Embedded - Microcontroller,

Details	
Product Status	Discontinued at Digi-Key
Module/Board Type	MPU Core
Core Processor	Zynq UltraScale+ XCZU3CG-1SFVC784E
Co-Processor	-
Speed	-
Flash Size	128MB
RAM Size	1GB
Connector Type	B2B
Size / Dimension	1.97" x 1.57" (50mm x 40mm)
Operating Temperature	0°C ~ 85°C
Purchase URL	https://www.e-xfl.com/product-detail/trenz-electronic/te0820-02-03cg-1ea

1 Table of Contents

2 Overview

Refer to https://wiki.trenz-electronic.de/display/PD/TE0820+TRM for online version of this manual and additional technical documentation of the product.
The Trenz Electronic TE0820 is 4 x 5 cm standard footprint MPSoC module integrating a Xilinx Zynq UltraScale+ with up to 4 GByte 32-Bit DDR4 SDRAM, max. 512 MByte SPI Boot Flash memory for configuration and operation and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/Os is provided via rugged high-speed stacking strips. All Trenz Electronic SoMs in 4 x 5 cm form factor are mechanically compatible.

2.1 Key Features

- Xilinx Zynq UltraScale+ MPSoC 784-pin package (ZU2EG, option for ZU5EV)
  - Quad-core or dual-core Cortex-A53 64-bit ARM v8 application processing unit (APU) (depends on assembly variant CG,EG,EV)
  - Dual Cortex-R5 32-bit ARM v7 real-time processing unit (RPU)
  - Four high-speed serial I/O (HSSIO) interfaces supporting following protocols:
    - PCI Express® interface version 2.1 compliant
    - SATA 3.1 specification compliant interface
    - DisplayPort source-only interface with video resolution up to 4k x 2k
    - USB 3.0 specification compliant interface implementing a 5 Gbit/s line rate
    - 1 GB/s serial GMII interface
  - 132 x HP PL I/Os (3 banks)
  - 14 x PS MIOs (6 of the MIOs intended for SD card interface in default configuration)
  - 4 x serial PS GTR transceivers
- 1 GByte DDR4 SDRAM, 4 GByte maximum
- Dual parallel SPI boot Flash, 512 MByte maximum
- 4 GByte eMMC (up to 64 GByte)
- GT reference clock input
- PLL for GT clocks (optional external reference)
- Gigabit Ethernet transceiver PHY (Marvell Alaska 88E1512)
- MAC address serial EEPROM with EUI-48™ node identity (Microchip 24AA025E48)
- Hi-speed USB 2.0 ULPI transceiver with full OTG support (Microchip USB3320C)
- Programmable quad clock generator
- Plug-on module with 2 x 100-pin and 1 x 60-pin high-speed hermaphroditic strips
- All power supplies on board
- Size: 50 x 40 mm

2.2 Block Diagram

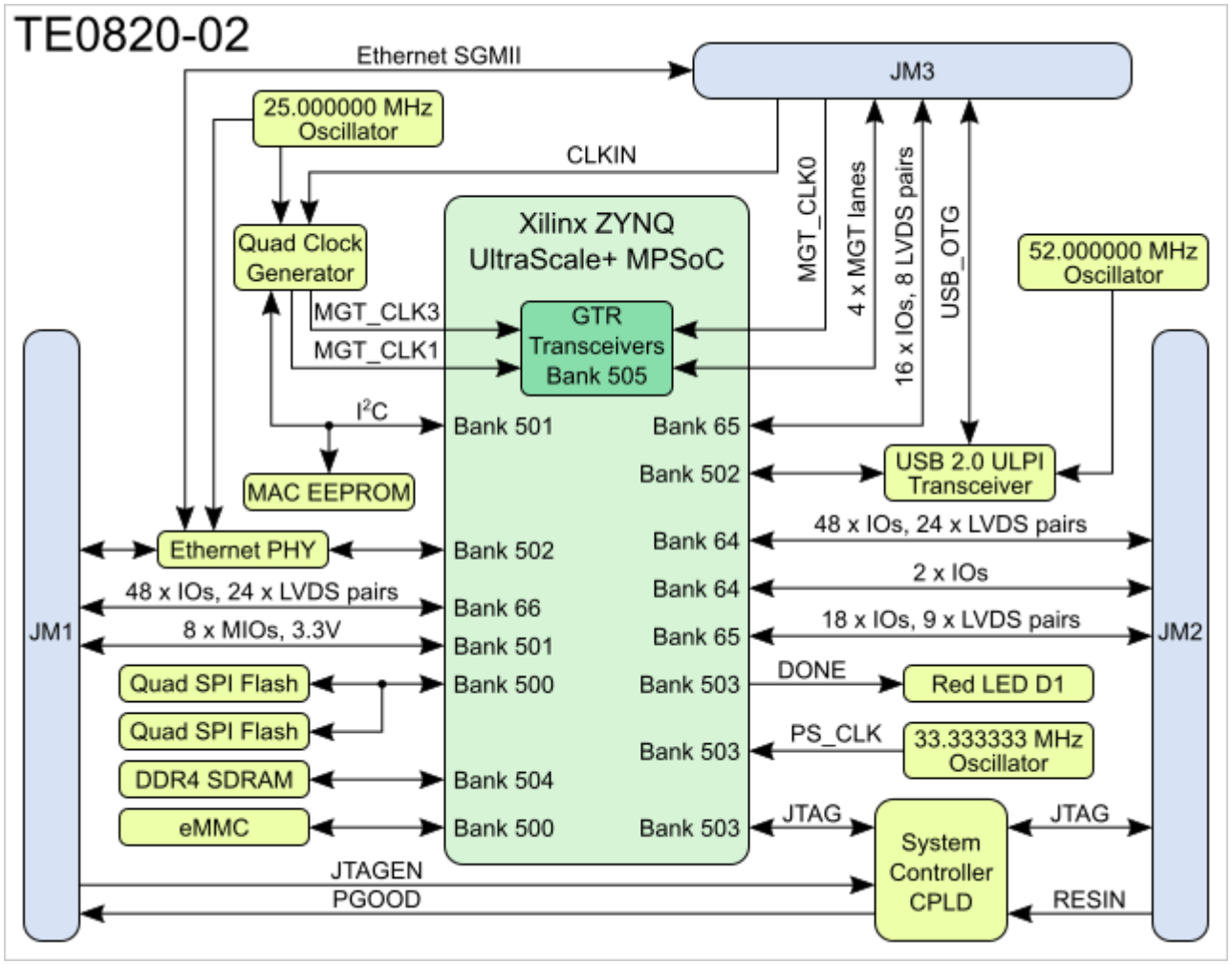
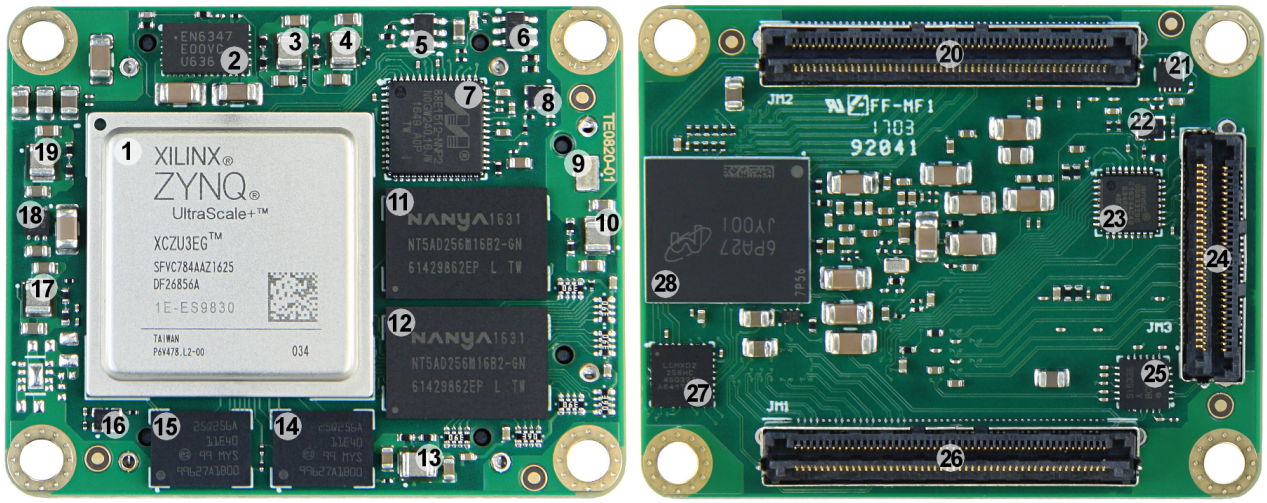


Figure 1: TE020-02 block diagram.

2.3 Main Components



3 Boot Process

Two different firmware versions are available, one with the QSPI boot option and other with the SD Card boot option.

B2B JM1 MODE Pin	QSPI Firmware Version	SD Card Firmware Version
Low	JTAG	Boot from SD Card
High	Boot from Flash	JTAG

Table 2: Boot mode pin description.

For more information refer to the TE0820 CPLD - BootMode section.

4 Signals, Interfaces and Pins

4.1 Board to Board (B2B) I/Os

Zynq MPSoC's I/O banks signals connected to the B2B connectors:

Bank	Type	B2B Connector	I/O Signal Count	Voltage	Notes
64	HP	JM2	48	User	Max voltage 1.8V.
64	HP	JM2	2	User	Max voltage 1.8V.
65	HP	JM2	18	User	Max voltage 1.8V.
65	HP	JM3	16	User	Max voltage 1.8V.
66	HP	JM1	48	User	Max voltage 1.8V.
501	MIO	JM1	6	3.3V	-
505	GTR	JM3	4 lanes	N/A	-
505	GTR CLK	JM3	1 differential input	N/A	-

Table 3: General overview of board to board I/O signals.

For detailed information about the pin-out, please refer to the Pin-out table.

4.2 MGT Lanes

The Xilinx Zynq UltraScale+ device used on the TE0820 module has 4 GTR transceivers. All 4 are wired directly to B2B connector JM3. MGT (Multi Gigabit Transceiver) lane consists of one transmit and one receive (TX/RX) differential pairs, four signals total per one MGT lane. Following table lists lane number, FPGA bank number, transceiver type, signal schematic name, board-to-board pin connection and FPGA pins connection:

Lane	Bank	Type	Signal Name	B2B Pin	FPGA Pin
0	505	GTR	• B505_RX0_P • B505_RX0_N • B505_TX0_P • B505_TX0_N	• JM3-26 • JM3-28 • JM3-25 • JM3-27	• PS_MGTRRXP0_505, F27 • PS_MGTRRXN0_505, F28 • PS_MGTRTXP0_505, E25 • PS_MGTRTXN0_505, E26
1	505	GTR	• B505_RX1_P • B505_RX1_N • B505_TX1_P • B505_TX1_N	• JM3-20 • JM3-22 • JM3-19 • JM3-21	• PS_MGTRRXP1_505, D27 • PS_MGTRRXN1_505, D28 • PS_MGTRTXP1_505, D23 • PS_MGTRTXN1_505, D24

Pin 89 JTAGEN of B2B connector JM1 is used to control which device is accessible via JTAG. If set to low or grounded, JTAG interface will be routed to the Xilinx Zynq MPSoC. If pulled high, JTAG interface will be routed to the System Controller CPLD.

4.4 System Controller CPLD I/O Pins

Special purpose pins are connected to System Controller CPLD and have following default configuration:

Pin Name	Mode	Function	Default Configuration
EN1	Input	Power Enable	No hard wired function on PCB. When forced low, pulls up PGOOD, goes low without effect on power management.
PGOOD	Output	Power Good	Active high when all on-module power supplies are working properly.
NOSEQ	-	-	No function.
RESIN	Input	Reset	Active low reset, gated to POR_B.
JTAGEN	Input	JTAG Select	Low for normal operation, high for CPLD JTAG access.

Table 7: System Controller CPLD special purpose pins.

See also TE0820 CPLD.

4.5 Default PS MIO Mapping

PS MIO	Function	B2B Pin	Connected to	PS MIO	Function	B2B Pin	Connected to
0	SPI0	-	U7-B2, CLK	**40..45**	-	-	Not connected
1	SPI0	-	U7-D2, DO/IO1	**46**	SD	JM1-17	B2B, SD_DAT3
2	SPI0	-	U7-C4, WP/IO2	**47**	SD	JM1-19	B2B, SD_DAT2
3	SPI0	-	U7-D4, HOLD/IO3	**48**	SD	JM1-21	B2B, SD_DAT1
4	SPI0	-	U7-D3, DI/IO0	**49**	SD	JM1-23	B2B, SD_DAT0
5	SPI0	-	U7-C2, CS	**50**	SD	JM1-25	B2B, SD_CMD
6	N/A	-	Not connected	**51**	SD	JM1-27	B2B, SD_CLK
7	SPI1	-	U17-C2, CS	**52**	USB_PHY	-	U18-31, OTG-DIR
8	SPI1	-	U17-D3, DI/IO0	**53**	USB_PHY	-	U18-31, OTG-DIR

9	SPI1	-	U17-D2, DO/IO1	**54**	USB_PHY	-	U18-5, OTG-DATA2
10	SPI1	-	U17-C4, WP/IO2	**55**	USB_PHY	-	U18-2, OTG-NXT
11	SPI1	-	U17-D4, HOLD/IO3	**56**	USB_PHY	-	U18-3, OTG-DATA0
12	SPI1	-	U17-B2, CLK	**57**	USB_PHY	-	U18-4, OTG-DATA1
13..20	eMMC	-	U6, MMC-D0..D7	**58**	USB_PHY	-	U18-29, OTG-STP
21	eMMC	-	U6, MMC-CMD	**59**	USB_PHY	-	U18-6, OTG-DATA3
22	eMMC	-	U6, MMC-CLKR	**60**	USB_PHY	-	U18-7, OTG-DATA4
23	eMMC	-	U6, MMC-RST	**61**	USB_PHY	-	U18-9, OTG-DATA5
24	ETH	-	U8, ETH-RST	**62**	USB_PHY	-	U18-10, OTG-DATA6
25	USB_PHY	-	U18, OTG-RST	**63**	USB_PHY	-	U18-13, OTG-DATA7
26	MIO	JM1-95	B2B	**64**	ETH	-	U8-53, ETH-TXCK
27	MIO	JM1-93	B2B	**65..66**	ETH	-	U8-50..51, ETH-TXD0..1
28	MIO	JM1-99	B2B	**67..68**	ETH	-	U8-54..55, ETH-TXD2..3
29	MIO	JM1-99	B2B	**69**	ETH	-	U8-56, ETH-TXCTL
30	MIO	JM1-92	B2B (UART RX)	**70**	ETH	-	U8-46, ETH-RXCK
31	MIO	JM1-85	B2B (UART TX)	**71..72**	ETH	-	U8-44..45, ETH-RXD0..1
32	MIO	JM1-91	B2B	**73..74**	ETH	-	U8-47..48, ETH-RXD2..3
33	MIO	JM1-87	B2B	**75**	ETH	-	U8-43, ETH-RXCTL
34..37	-	-	Not connected	**76**	ETH	-	U8-7, ETH-MDC

CLKOUT	MIO52	-	Connected to 1.8V, selects reference clock operation mode.
DP, DM	-	OTG_D_P, OTG_D_N	USB data lines routed to B2B connector JM3 pins 47 and 49.
CPEN	-	VBUS_V_EN	External USB power switch active high enable signal, routed to JM3 pin 17.
VBUS	-	USB_VBUS	Connect to USB VBUS via a series of resistors, see reference schematics, routed to JM3 pin 55.
ID	-	OTG_ID	For an A-device connect to ground, for a B-device left floating. routed from JM3 pin 23.

Table 10: General overview of the USB PHY signals.

4.8 I2C Interface

On-board I^2C devices are connected to MIO38 (SCL) and MIO39 (SDA) which are configured as I^2C1 by default. Addresses for on-board I^2C slave devices are listed in the table below:

I2C Device	I2C Address	Notes
Si5338A PLL	0x70	-
EEPROM	0x53	-

Table 11: Address table of the I^2C bus slave devices.

5 On-board Peripherals

5.1 System Controller CPLD

The System Controller CPLD (U21) is provided by Lattice Semiconductor LCMXO2-256HC (MachXO2 product family). It is the central system management unit with module specific firmware installed to monitor and control various signals of the FPGA, on-board peripherals, I/O interfaces and module as a whole.

See also TE0820 System Controller CPLD page.

5.2 eMMC Flash Memory

eMMC Flash memory device(U6) is connected to the ZynqMP PS MIO bank 500 pins MIO13..MIO23. eMMC chips MTFC4GACAJCN-4M IT (FLASH - NAND Speicher-IC 32 Gb (4 G x 8) MMC) is used.

5.3 DDR4 Memory

By default TE0820-02 module has two 16-bit wide Nanya NT5AD256M16B2 DDR4 SDRAM chips arranged into 32-bit wide memory bus providing total of 1 GBytes of on-board RAM. Different memory sizes are available optionally.

5.4 Quad SPI Flash Memory

Two quad SPI compatible serial bus flash N25Q256A memory chips are provided for FPGA configuration file storage. After configuration completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency.

5.5 Gigabit Ethernet PHY

On-board Gigabit Ethernet PHY (U8) is provided with Marvell Alaska 88E1512 IC (U8). The Ethernet PHY RGMII interface is connected to the ZynqMP Ethernet3 PS GEM3. I/O voltage is fixed at 1.8V for HSTL signaling. The reference clock input of the PHY is supplied from an on-board 25.000000 MHz oscillator (U21).

5.6 High-speed USB ULPI PHY

Hi-speed USB ULPI PHY (U32) is provided with USB3320 from Microchip. The ULPI interface is connected to the Zynq PS USB0 via MIO28..39, bank 501 (see also section). The I/O voltage is fixed at 1.8V and PHY reference clock input is supplied from the on-board 52.000000 MHz oscillator (U33).

5.7 MAC Address EEPROM

A Microchip 24AA025E48 serial EEPROM (U25) contains a globally unique 48-bit node address, which is compatible with EUI-48(TM) specification. The device is organized as two blocks of 128 x 8-bit memory. One of the blocks stores the 48-bit node address and is write protected, the other block is available for application use. It is accessible over I^2C bus with slave device address 0x53.

5.8 Programmable Clock Generator

There is a Silicon Labs I^{2}C programmable clock generator Si5338A (U10) chip on the module. It's output frequencies can be programmed using the I^{2}C bus address 0x70 or 0x71. Default address is 0x70, IN4/I2C_LSB pin must be set to high for address 0x71.

A 25.000000 MHz oscillator is connected to the pin IN3 and is used to generate the output clocks. The oscillator has its output enable pin permanently connected to 1.8V power rail, thus making output frequency available as soon as 1.8V is present. Three of the Si5338 clock outputs are connected to the FPGA. One is connected to a logic bank and the other two are connected to the GTR banks. It is possible to use the clocks connected to the GTR bank in the user's logic design. This is achieved by instantiating a IBUFDSGTE buffer in the design.

Once running, the frequency and other parameters can be changed by programming the device using the I^{2}C bus connected between the FPGA (master) and clock generator (slave). For this, proper I^{2}C bus logic has to be implemented in FPGA.

Signal	Frequency	Notes
IN1/IN2	-	Not used (external clock signal supply).
IN3	25.000000 MHz	Fixed input clock signal from reference clock generator SiT8008BI-73-18S-25.000000E (U11).
IN4	-	LSB of the default I^{2}C address, wired to ground mean address is 0x70.
IN5	-	Not connected.
IN6	-	Wired to ground.
CLK0 A/B	-	Bank 65 clock input, pins K9 and J9.
CLK1 A/B	-	MGT reference clock 3 to FPGA Bank 505 MGT.
CLK2 A/B	-	MGT reference clock 1 to FPGA Bank 505 MGT.
CLK3 A/B	-	Not connected.

Table 12: General overview of the on-board quad clock generator I/O signals.

5.9 Oscillators

The module has following reference clock signals provided by on-board oscillators and external source from carrier board:

6 Power and Power-on Sequence

6.1 Power Supply

Power supply with minimum current capability of 3A for system startup is recommended.

6.2 Power Consumption

Power Input	Typical Current
VIN	TBD*
3.3VIN	TBD*

Table 14: Power consumption.

*TBD - To be determined.

6.3 Power Distribution Dependencies

Module has two power input rails which can be connected to the single power source.

6.4 Power-On Sequence

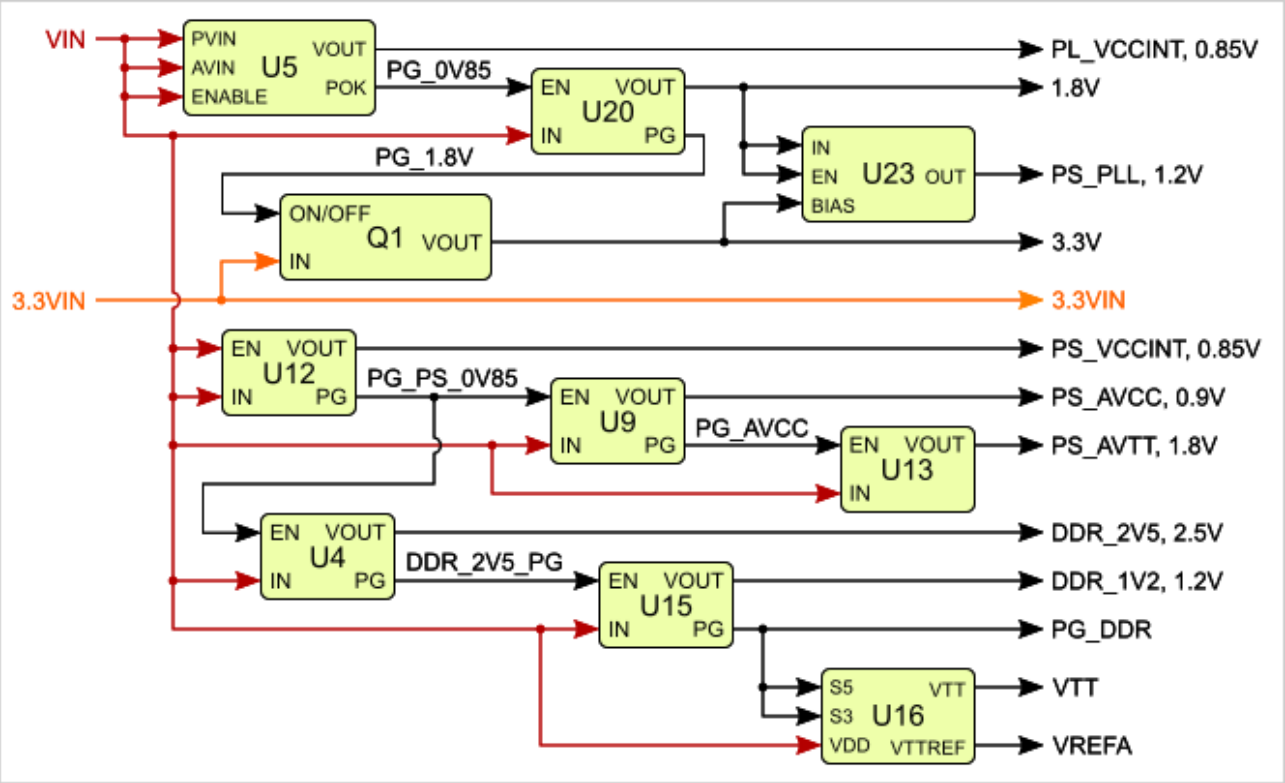


Figure 4: TE0820-02 power-on sequence diagram.

For highest efficiency of the on-board DC-DC regulators, it is recommended to use one 3.3V power source for both VIN and 3.3VIN power rails. Although VIN and 3.3VIN can be powered up in any order, it is recommended to power them up simultaneously.

It is important that all carrier board I/Os are 3-stated at power-on until System Controller CPLD sets PGOOD signal high (B2B connector JM1, pin 30), or 3.3V is present on B2B connector JM2 pins 10 and 12, indicating that all on-module voltages have become stable and module is properly powered up.

See Xilinx datasheet DS925 for additional information. User should also check related carrier board documentation when choosing carrier board design for TE0715 module.

6.5 Power Rails

Power Rail Name on B2B Connector	JM1 Pins	JM2 Pins	Direction	Notes
VIN	1, 3, 5	2, 4, 6, 8	Input	Supply voltage from the carrier board.
3.3V	-	10, 12	Output	Internal 3.3V voltage level.
3.3VIN	13, 15, 91	-	Input	Supply voltage from the carrier board.

VCCO_64	-	7, 9	Input	High performance I/O bank voltage.
VCCO_65	-	5	Input	High performance I/O bank voltage.
VCCO_66	9, 11	-	Input	High performance I/O bank voltage.

Table 15: TE0820-02 power rails.

6.6 Bank Voltages

Bank	Name on Schematic	Voltage	Range
64 HP	VCCO_64	User	HP: 1.0V to 1.8V
65 HP	VCCO_65	User	HP: 1.0V to 1.8V
66 HP	VCCO_66	User	HP: 1.0V to 1.8V
500 PSMIO	VCCO_PSIO0_500	1.8V	-
501 PSMIO	VCCO_PSIO1_501	3.3V	-
502 PSMIO	VCCO_PSIO2_502	1.8V	-
503 PSCONFIG	VCCO_PSIO3_503	1.8V	-
504 PSDDR	VCCO_PSDDR_504	1.2V	-

Table 16: TE0820-02 I/O bank voltages.

See Xilinx Zynq UltraScale+ datasheet DS925 for the voltage ranges allowed.

7.3 Current Rating

Current rating of Samtec Razor Beam™ LSHM B2B connectors is 2.0A per pin (2 adjacent pins powered).

7.4 Connector Mechanical Ratings

- Shock: 100G, 6 ms Sine
- Vibration: 7.5G random, 2 hours per axis, 3 axes total

7.5 Manufacturer Documentation

Geändert
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz
07 04, 2016 by Thorsten Trenz

8 Variants Currently In Production

Module Variant	MPSoC	RAM	SPI Flash	Temperature Range	Note
TE0820-02-02CG-1E	XC**ZU2CG**-1SFVC784E	1 GByte DDR4	64 MByte	Extended	
TE0820-02-03CG-1E	XC**ZU3CG**-1SFVC784E	1 GByte DDR4	64 MByte	Extended	
TE0820-02-02EG-1E	XC**ZU2EG**-1SFVC784E	1 GByte DDR4	64 MByte	Extended	
TE0820-02-03EG-1E	XC**ZU3EG**-1SFVC784E	1 GByte DDR4	64 MByte	Extended	
TE0820-02-02EG-1E3	XC**ZU2EG**-1SFVC784E	1 GByte DDR4	64 MByte	Extended	2,5mm Samtec connector
TE0820-02-03EG-1E3	XC**ZU3EG**-1SFVC784E	1 GByte DDR4	64 MByte	Extended	2,5mm Samtec connector

Table 17: TE0820-02 variants.

9 Technical Specifications

9.1 Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
VIN supply voltage	-0.3	7.0	V	See EN6347QI and TPS82085SIL datasheets.
3.3VIN supply voltage	-0.1	3.75	V	See LCMXO2-256HC and TPS27082L datasheet.
PS I/O supply voltage, VCCO_PSIO	-0.5	3.630	V	Xilinx document DS925
PS I/O input voltage	-0.5	VCCO_PSIO + 0.55	V	Xilinx document DS925
HP I/O bank supply voltage, VCCO	-0.5	2.0	V	Xilinx document DS925
HP I/O bank input voltage	-0.55	VCCO + 0.55	V	Xilinx document DS925
Voltage on module JTAG pins	-0.4	VCCO_0 + 0.55	V	VCCO_0 is 1.8V or 3.3V nominal. Xilinx document DS925
Storage temperature	-40	+85	°C	See eMMC datasheet.

Table 18: Module absolute maximum ratings.

9.2 Recommended Operating Conditions

Parameter	Min	Max	Units	Notes
VIN supply voltage	2.5	6.6	V	See TPS82085S datasheet
3.3VIN supply voltage	2.375	3.6	V	See LCMXO2-256HC datasheet
PS I/O supply voltage, VCCO_PSIO	1.710	3.465	V	Xilinx document DS925
PS I/O input voltage	–0.20	VCCO_PSIO + 0.20	V	Xilinx document DS925
HP I/O banks supply voltage, VCCO	1.14	3.465	V	Xilinx document DS925

HP I/O banks input voltage	-0.20	VCCO + 0.20	V	Xilinx document DS925
Voltage on module JTAG pins	3.135	3.465	V	For a module variant with 3.3V CONFIG bank option

Table 19: Recommended operating conditions.

⚠ See Xilinx datasheet DS925 for more information about absolute maximum and recommended operating ratings for the Zynq UltraScale+ chips.

9.3 Operating Temperature Ranges

Extended grade: 0°C to +85°C.

Module operating temperature range depends also on customer design and cooling solution. Please contact us for options.

9.4 Physical Dimensions

- Module size: 50 mm × 40 mm. Please download the assembly diagram for exact numbers.
- Mating height with standard connectors: 8 mm
- PCB thickness: 1.6 mm
- Highest part on PCB: approximately 5 mm. Please download the step model for exact numbers.

All dimensions are shown in millimeters. Additional sketches, drawings and schematics can be found here.

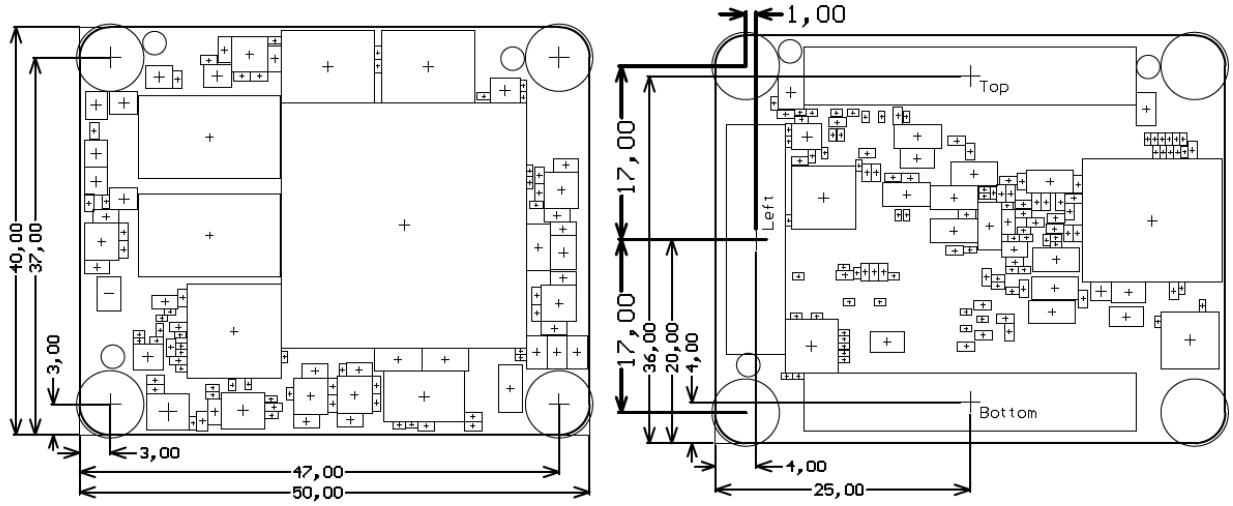


Figure 5: TE0820 module physical dimensions.

10 Revision History

10.1 Hardware Revision History

Date	Revision	Notes	PCN Link	Documentation Link
2017-08-17	02	--		TE0820-02
2016-12-23	01	Prototype only		TE0820-01

Table 20: Hardware revision history table.

Hardware revision number is written on the PCB board next to the module model number separated by the dash.

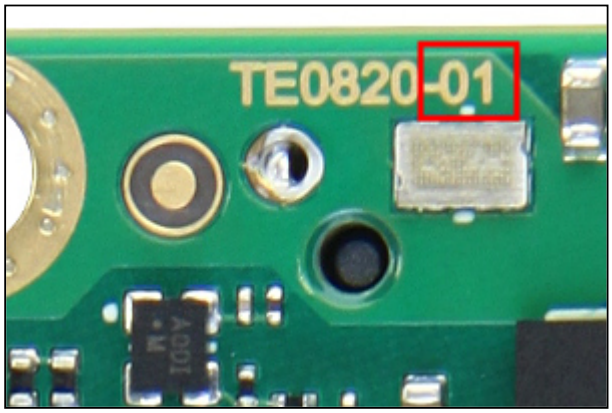


Figure 6: TE0820 module hardware revision.

10.2 Document Change History

Date	Revision	Contributors	Description
2017-11-20	v.51	John Hartfiel	• Correction Default MIO Configuration Table
2017-11-10	v.50	John Hartfiel	• Replace B2B connector section
2017-10-18	v.49	John Hartfiel	• add eMMC section
2017-09-25	v.48	John Hartfiel	• Correction in the "Board to Board (B2B) I/Os" section • Update in the "Variants Currently In Production" section
2017-09-18	v.47	John Hartfiel	• Update PS MIO table

2017-08-30	v.46	Jan Kumann	• MGT lanes section added.
2017-08-24	v.36	John Hartfiel	• Correction in the "Key Features" section.
2017-08-21	v.34	John Hartfiel	• "Initial delivery state" section updated.
2017-08-21	v.33	Jan Kumann	• HW revision 02 block diagram added. • Power distribution and power-on sequence diagram added. • System Controller CPLD and DDR4 SDRAM sections added. • TRM update to the template revision 1.6 • Weight section removed. • Few minor corrections.
2017-08-18	v.7	John Hartfiel	• Style changes • Updated "Boot Mode", "HW Revision History", "Variants Currently In Production" sections • Correction of MIO SD Pin-out, System Controller chapter • Update and new sub-sections on "On Board Peripherals and Interfaces" sections
2017-08-07	v.5	Jan Kumann	Initial version.

Table 21: Document change history.

compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the European Chemicals Agency (ECHA).

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.